

Normally-OFF Trench Silicon Carbide Power JFET

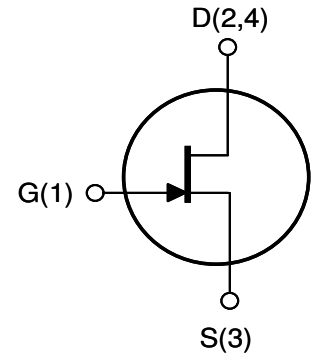
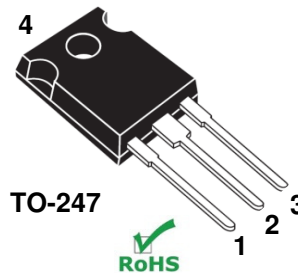
Features:

- Compatible with Standard Gate Driver ICs
- Positive Temperature Coefficient for Ease of Paralleling
- Temperature Independent Switching Behavior
- 175 °C Maximum Operating Temperature
- $R_{DS(on)max}$ of 0.550 Ω
- Voltage Controlled
- Low Gate Charge
- Low Intrinsic Capacitance

Applications:

- Flyback Auxillary Power Supplies for:
 - Solar inverters
 - Motor Drives
 - High Voltage SMPS
 - High Voltage UPS

Product Summary		
BV_{DS}	1700	V
$R_{DS(ON)max}$	0.550	Ω
$E_{TS,typ}$	74	μJ



Internal Schematic

MAXIMUM RATINGS

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	$I_D, T_j=125$	$T_j = 125\text{ }^\circ\text{C}$	4	A
	$I_D, T_j=175$	$T_j = 175\text{ }^\circ\text{C}$	3	
Pulsed Drain Current ⁽¹⁾	I_{DM}	$T_j = 25\text{ }^\circ\text{C}$	8	A
Short Circuit Withstand Time	t_{SC}	$V_{DD} < 800\text{ V}, T_C < 125\text{ }^\circ\text{C}$	TBD	μs
Power Dissipation	P_D	$T_C = 25\text{ }^\circ\text{C}$	58	W
Gate-Source Voltage	V_{GS}	AC ⁽²⁾	-15 to +15	V
Operating and Storage Temperature	T_j, T_{stg}		-55 to +175	$^\circ\text{C}$
Lead Temperature for Soldering	T_{sold}	1/8" from case < 10 s	260	$^\circ\text{C}$

⁽¹⁾ Pulse width limited by maximum junction temperature

⁽²⁾ $R_{gEXT} = 1\ \Omega, t_p \leq 200\text{ ns}$, see Figure 6 for static conditions

THERMAL CHARACTERISTICS

Parameter	Symbol	Value		Unit
		Typ	Max	
Thermal Resistance, junction-to-case	R_{thJC}	-	2.6	$^\circ\text{C} / \text{W}$
Thermal Resistance, junction-to-ambient	R_{thJA}	-	50	

ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Conditions	Value			Unit
			Min	Typ	Max	

Off Characteristics

Drain-Source Blocking Voltage	BV_{DS}	$V_{GS} = 0\text{ V}, I_D = 200\ \mu\text{A}$	1700	-	-	V
Total Drain Leakage Current	I_{DSS}	$V_{DS} = 1700\text{ V}, V_{GS} = 0\text{ V}, T_j = 25^\circ\text{C}$	-	10	200	μA
		$V_{DS} = 1700\text{ V}, V_{GS} = 0\text{ V}, T_j = 175^\circ\text{C}$	-	50	-	
		$V_{DS} = 1700\text{ V}, V_{GS} \leq -15\text{ V}, T_j = 25^\circ\text{C}$	-	10	-	
		$V_{DS} = 1700\text{ V}, V_{GS} \leq -15\text{ V}, T_j = 175^\circ\text{C}$	-	30	-	
Total Gate Reverse Leakage	I_{GSS}	$V_{GS} = -15\text{ V}, V_{DS} = 0\text{ V}$	-	-0.02	-0.1	mA
		$V_{GS} = -15\text{ V}, V_{DS} = 1700\text{ V}$	-	-0.02	-	

On Characteristics

Drain-Source On-resistance	$R_{DS(on)}$	$I_D = 3\text{ A}, V_{GS} = 3\text{ V}, T_j = 25^\circ\text{C}$	-	0.45	0.55	Ω
		$I_D = 3\text{ A}, V_{GS} = 3\text{ V}, T_j = 125^\circ\text{C}$	-	1.08	-	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = 1\text{ V}, I_D = 10\text{ mA}$	-	1.00	-	V
Gate Forward Current	I_{GFWD}	$V_{GS} = 3\text{ V}$	-	135	-	mA
Gate Resistance	R_G	$f = 1\text{ MHz}, \text{ drain-source shorted}$	-	15	-	Ω
	$R_{G(ON)}$	$V_{GS} > 2.7\text{ V}; \text{ See Figure 6}$	-	1	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{DD} = 300\text{ V}$	-	170	-	pF
Output Capacitance	C_{oss}		-	20	-	
Reverse Transfer Capacitance	C_{rss}		-	17	-	
Effective Output Capacitance, energy related	$C_{o(er)}$	$V_{DS} = 0\text{ V to } 600\text{ V}, V_{GS} = 0\text{ V}$	-	20	-	

Switching Characteristics

Turn-on Delay	t_{on}	$V_{DS} = 850\text{ V}, I_D = 3\text{ A},$ Inductive Load, $T_j = 25^\circ\text{C}$ Gate Driver = +15 V unipolar $R_{gEXT} = 20\ \Omega$	-	12	-	ns
Rise Time	t_r		-	14	-	
Turn-off Delay	t_{off}		-	28	-	
Fall Time	t_f		-	30	-	
Turn-on Energy	E_{on}	See Figure 15 and application note AN-SS1 for gate drive recommendations	-	41	-	μJ
Turn-off Energy	E_{off}		-	33	-	
Total Switching Energy	E_{ts}		-	74	-	
Turn-on Delay	t_{on}	$V_{DS} = 850\text{ V}, I_D = 3\text{ A},$ Inductive Load, $T_j = 150^\circ\text{C}$ Gate Driver = +15 V unipolar $R_{gEXT} = 20\ \Omega$	-	TBD	-	ns
Rise Time	t_r		-	TBD	-	
Turn-off Delay	t_{off}		-	TBD	-	
Fall Time	t_f		-	TBD	-	
Turn-on Energy	E_{on}	See Figure 15 and application note AN-SS1 for gate drive recommendations	-	TBD	-	μJ
Turn-off Energy	E_{off}		-	TBD	-	
Total Switching Energy	E_{ts}		-	TBD	-	
Total Gate Charge	Q_g	$V_{DS} = 850\text{ V}, I_D = 1.5\text{ A},$ $V_{GS} = +2.5\text{ V}$	-	10	-	nC
Gate-Source Charge	Q_{gs}		-	8	-	
Gate-Drain Charge	Q_{gd}		-	1	-	

Figure 1. Typical Output Characteristics

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}; \text{parameter: } V_{GS}$

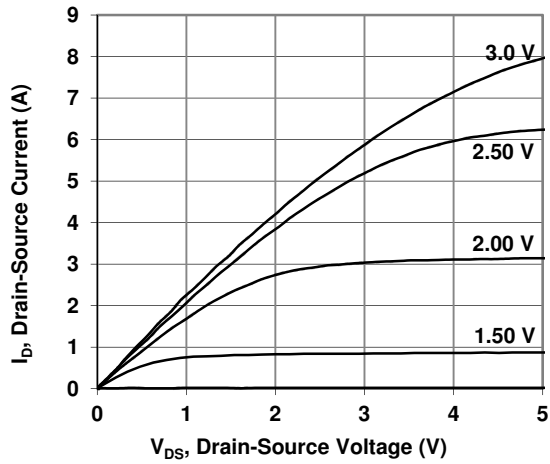


Figure 2. Typical Output Characteristics

$I_D = f(V_{DS}); T_j = 125\text{ }^\circ\text{C}; \text{parameter: } V_{GS}$

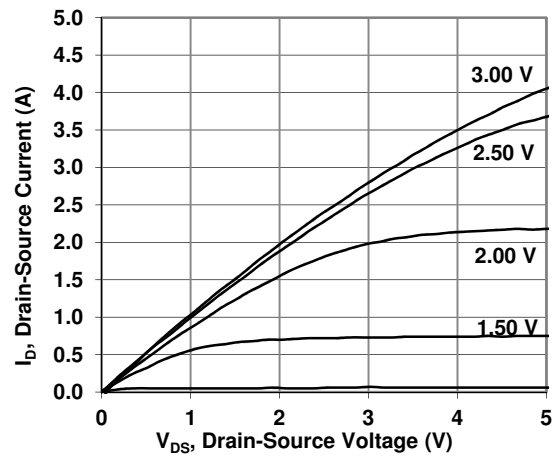


Figure 3. Typical Output Characteristics

$I_D = f(V_{DS}); T_j = 175\text{ }^\circ\text{C}; \text{parameter: } V_{GS}$

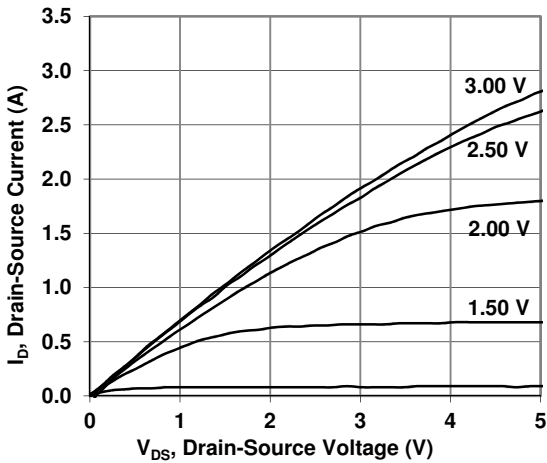


Figure 4. Safe Operating Area

$I_D = f(V_{DS}); T_C = 25\text{ }^\circ\text{C}$

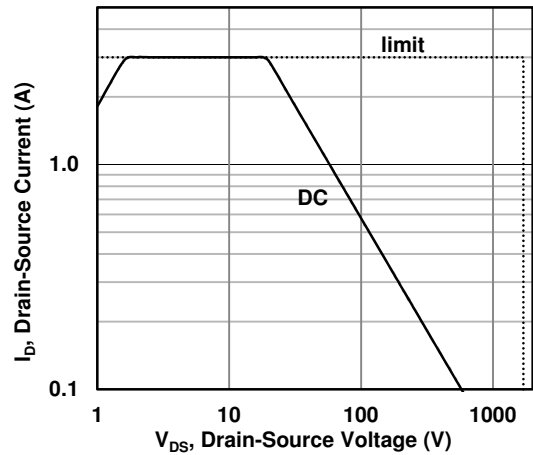


Figure 5. Typical Transfer Characteristics

$I_D = f(V_{GS}); V_{DS} = 5\text{ V}$

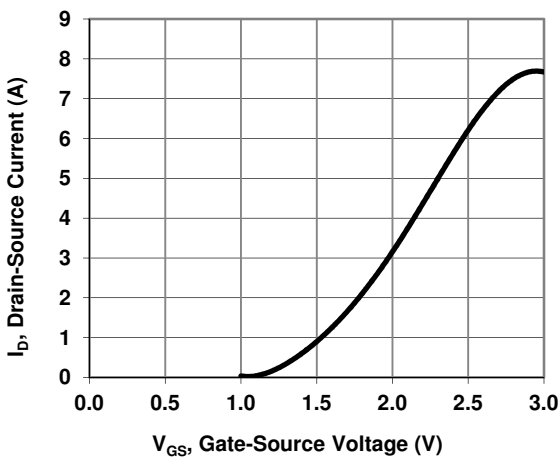


Figure 6. Gate-Source Current

$I_{GS} = f(V_{GS}); \text{parameter: } T_j$

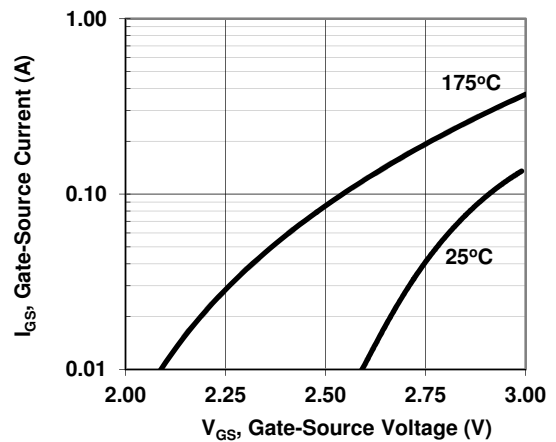


Figure 7. Drain-Source On-resistance

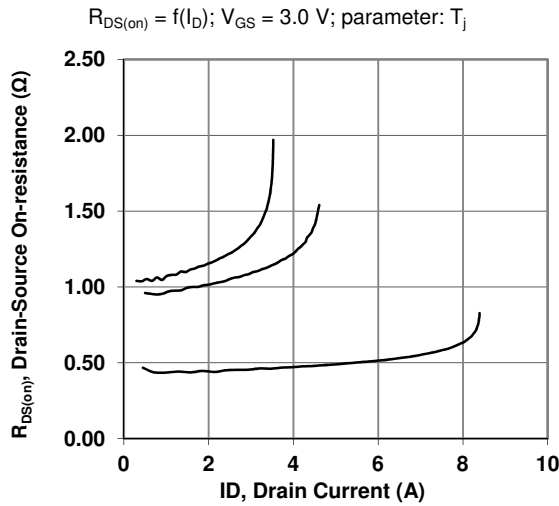


Figure 8. Drain-Source On-resistance

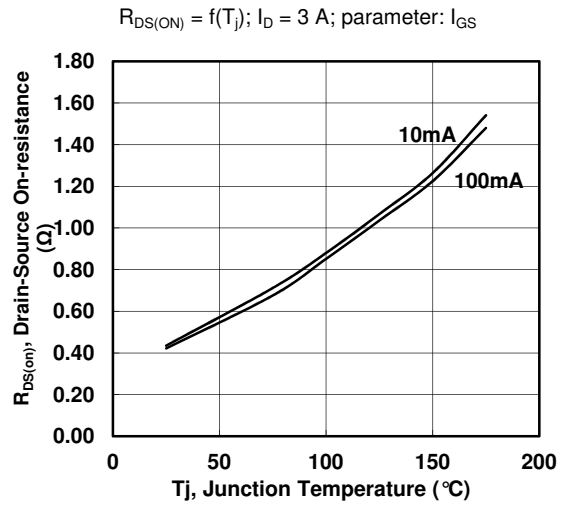


Figure 9. Drain-Source On-resistance

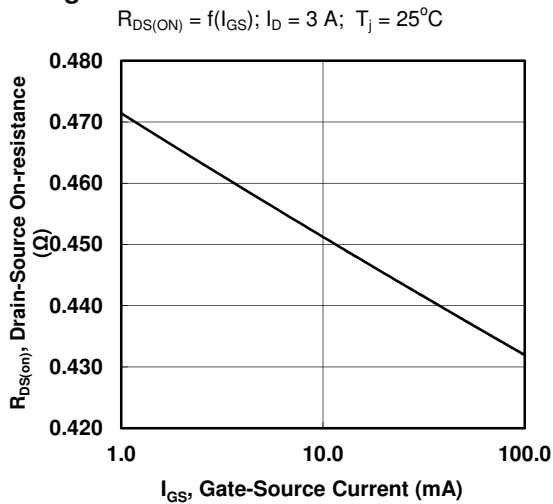


Figure 10. Typical Capacitance

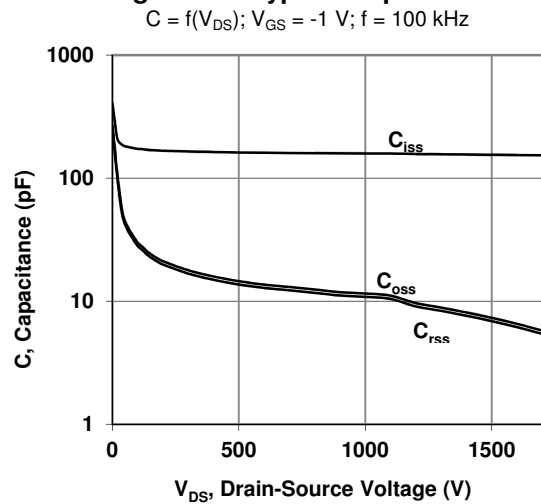


Figure 11. Gate Charge

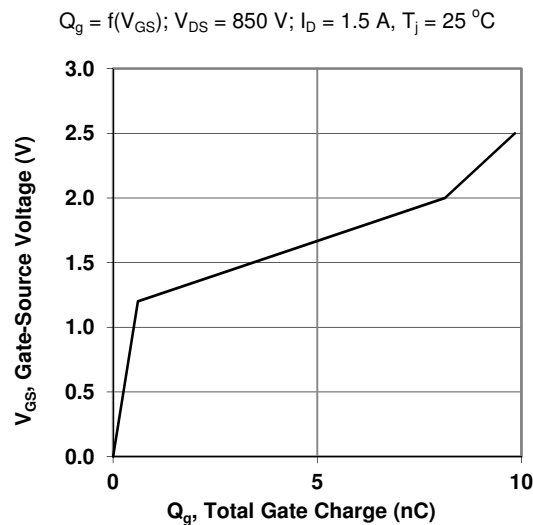


Figure 12. Gate Threshold Voltage

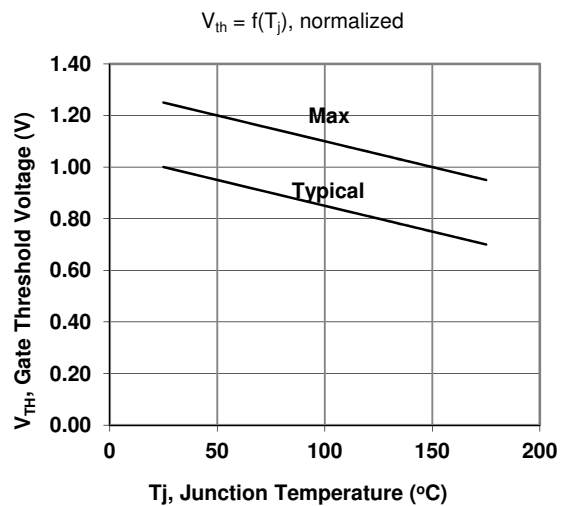


Figure 13. Drain-Source Leakage

$I_D = f(V_{DS}); V_{GS} = 0 \text{ V}; \text{parameter: } T_j$

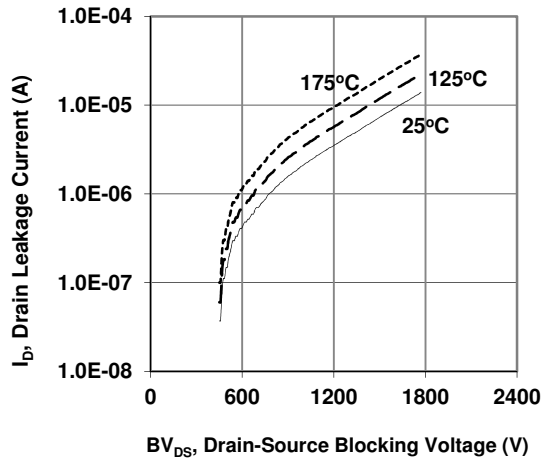


Figure 14. Switching Energy Losses

$E_s = f(I_D); V_{DS} = 850 \text{ V}; GD = +15 \text{ V}, R_{GEXT} = 20 \Omega; T_C = 25^\circ \text{C}$

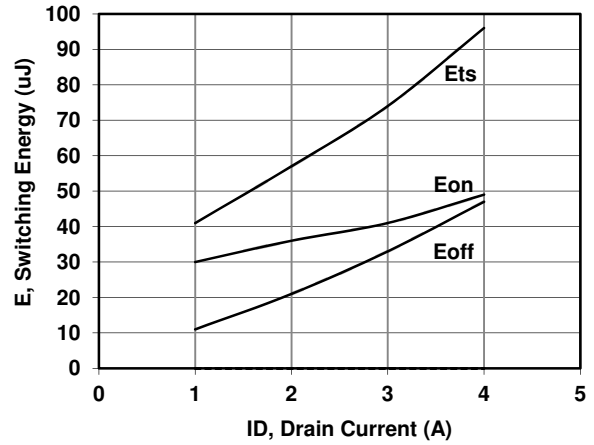
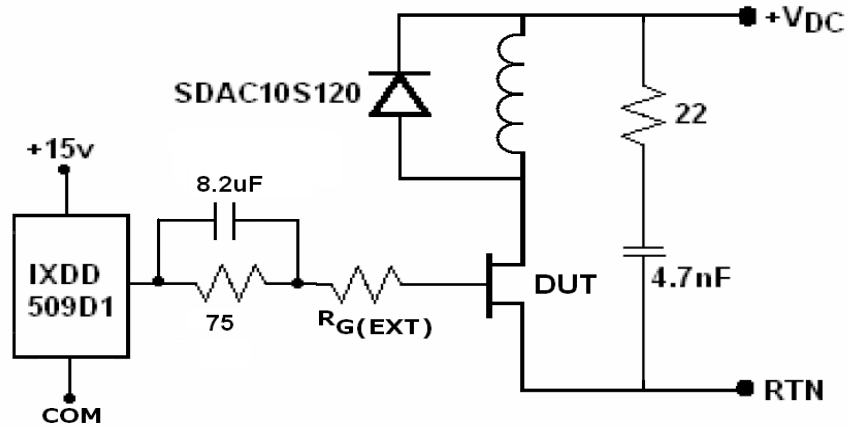
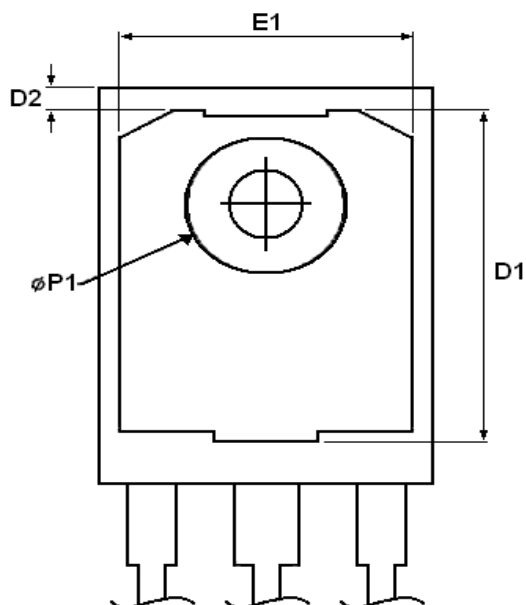
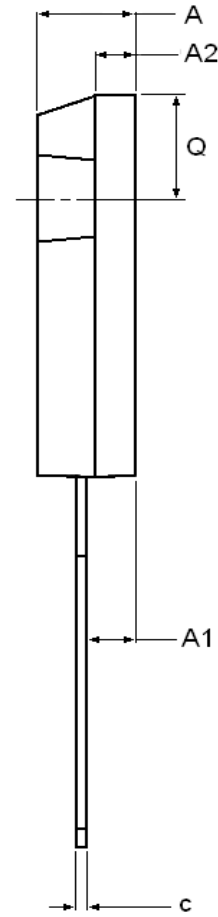
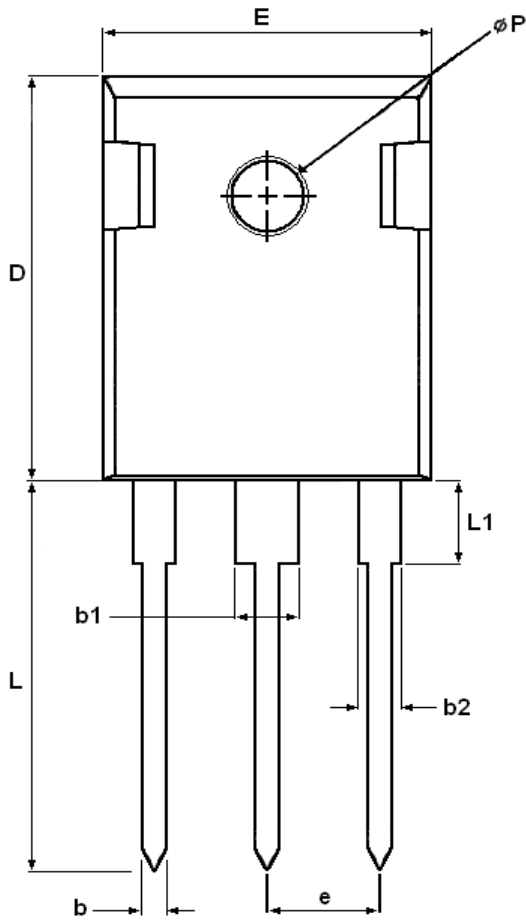


Figure 15. Inductive Load Switching Circuit



Package Dimensions: TO-247



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.903	5.157	0.193	0.203
A1	2.273	2.527	0.090	0.100
A2	1.853	2.108	0.073	0.083
b	1.073	1.327	0.042	0.052
b1	2.873	3.381	0.113	0.133
b2	1.903	2.386	0.042	0.052
c	0.600	0.752	0.024	0.029
D	20.823	21.077	0.820	0.830
D1	17.393	17.647	0.685	0.695
D2	1.063	1.317	0.042	0.052
e	5.450		0.215	
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
L	20.053	20.307	0.789	0.799
L1	4.168	4.472	0.165	0.175
Q	6.043	6.297	0.238	0.248
ØP	3.560	3.660	0.140	0.144
ØP1	7.063	7.317	0.278	0.288

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